Electronic Acknowledgement Receipt				
1022261				
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Methods of forming a contact hole in a semiconductor device				
Kwan-Ju Koh				
34431				
Alec Benjamin Plumb				
20067/OPP031477US				
12-APR-2006				
30-DEC-2003				
19:36:49				
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		OPP031477US.pdf	89365	yes	2

Multipart Description		
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### New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

#### National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.